pattern of a first object is projected onto a second object. The signal system is systemized to store data corresponding to a change in an exposure condition. The change in the exposure condition is produced in response to scan motion of at least one of the first and second stages and in accordance with one of scan acceleration and scan speed. The data is measured beforehand by obtaining data of a projected image of the pattern of the first object, being formed on the second object through the projection optical system, while scanningly moving at least one of the first and second stages. The signal system is further systemized to control a drive of the first and second stages in an actual exposure process while reflecting a correction value, as determined on the basis of the data stored, to the driving of at least one of the first and second stages. --

IN THE CLAIMS:

Please CANCEL claim 1 without prejudice to or disclaimer of the recited subject matter.

Please ADD new claims 19-22 as follows:

-- 19. A scan type exposure apparatus comprising:

a first stage on which a first object is placed;

a second stage on which a second object is placed;

a projection optical system for projecting a pattern of the first object on to

stages in a timed relation with each other, relative to said projection optical system, while

the pattern of the first object is projected by said projection optical system onto the second object; and

a signal system systemized to store data corresponding to a change in an exposure condition, wherein the change in the exposure condition is produced in response to scan motion of at least one of said first and second stages and in accordance with one of scan acceleration and scan speed, and wherein the data is measured beforehand by obtaining data of a projected image of the pattern of the first object, being formed on the second object through said projection optical system, while scanningly moving at least one of said first and second stages, said signal system further being systemized to control a drive of said first and second stages in an actual exposure process while reflecting a correction value, as determined on the basis of the data stored, to the driving of at least one of said first and second stages.

20. An apparatus according to claim 19, wherein the correction value is determined with respect to deviation of the projected image of the pattern of the first object, upon the second object.

21. An apparatus according to claim 19, wherein the correction value is determined with respect to a focus error of the projected image of the pattern of the first object, upon the second object.

22. A device manufacturing method comprising:

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a pattern exposure step for performing exposure by use of a scan type exposure apparatus including (i) a first stage on which a first object is placed, (ii) a second stage on which a second object is placed, (iii) a projection optical system for projecting a pattern of the first object onto the second object, (iv) a scanning mechanism arranged to scanningly move the first and second stages in a timed relation with each other, relative to the projection optical system, while the pattern of the first object is projected by the projection optical system onto the second object, and (v) a signal system systemized to store data corresponding to a change in an exposure condition, wherein the change in the exposure condition is produced in response to scan motion of at least one of the first and second stages and in accordance with one of scan acceleration and scan speed, and wherein the data is measured beforehand by obtaining data of a projected image of the pattern of the first object, being formed on the second object through the projection optical system, while scanningly moving at least one of the first and second stages, the signal system further being systemized to control drive of the first and second stages in an actual exposure process while reflecting a correction value, as determined on the basis of the data stored, to the driving of at least one of the first and second stages; and

a development step for developing the second object pattern exposed by the scan type exposure apparatus, wherein a circuit pattern can be formed on the basis of the developed exposed pattern. --